



Case No.: AMKOR-017A  
Patent Appln.

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JUL 23 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Jong Sik Paek	)	Group No.:	2812
Serial No.:	10/043,946	)	Examiner:	Simkovic, Viktor
Filed:	01/11/2002	)		
For:	SEMICONDUCTOR PACKAGE WITH STACKED DIES	)		
		)		
		)		

AMENDMENT IN RESPONSE TO RESTRICTION REQUIREMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the Restriction Requirement mailed July 17, 2002, in relation to the above-identified patent application, please amend the application as follows:

In the Claims:

Please cancel Claims 12-18.

Please add the following new claims into prosecution:

*sub 47* 19. (New) A semiconductor package comprising:

*a*  
a plurality of leads;

a first semiconductor die including a plurality of bond pads disposed thereon, the